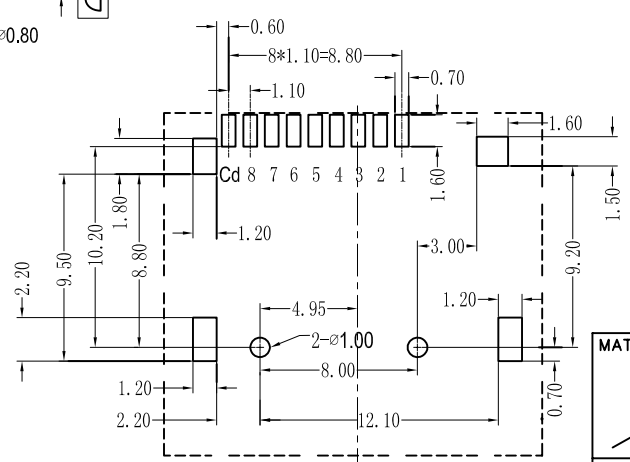
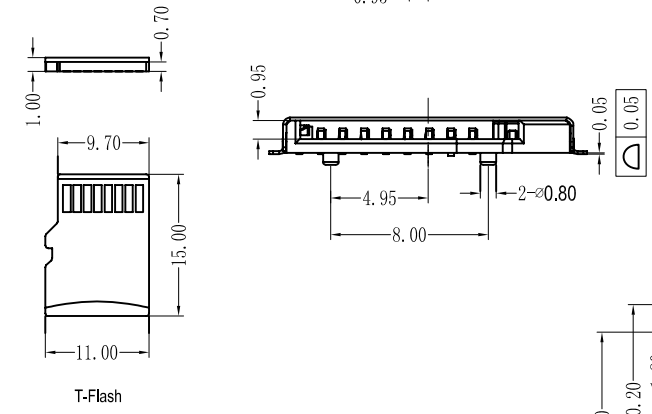
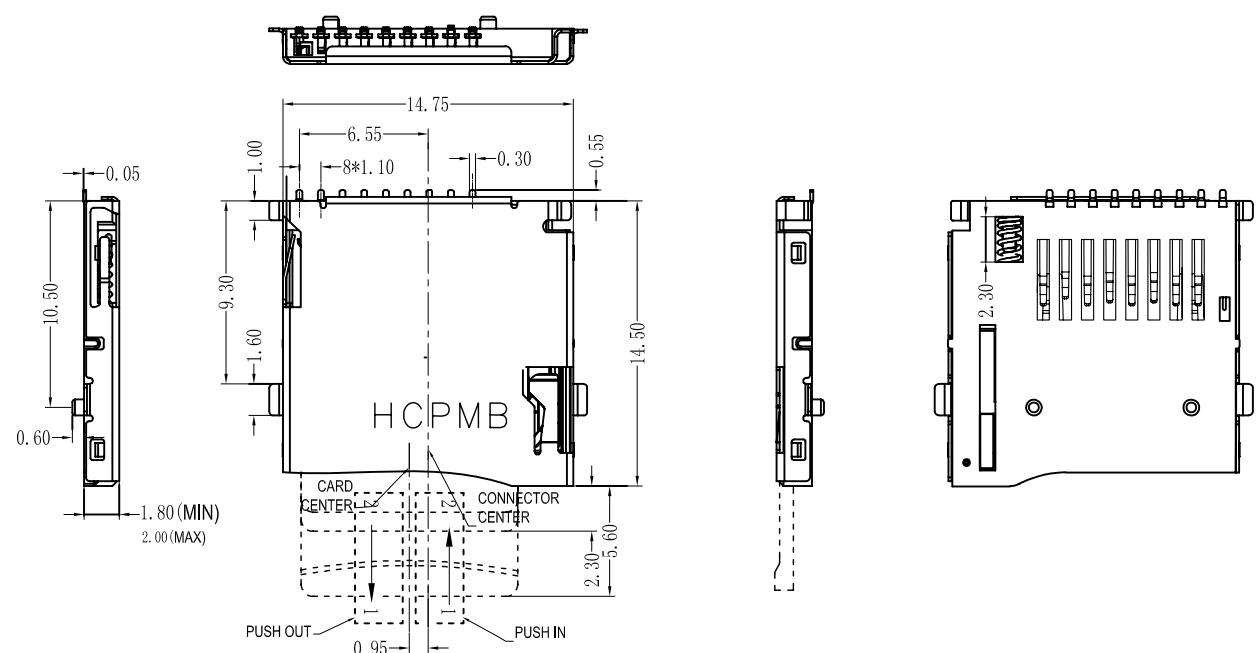


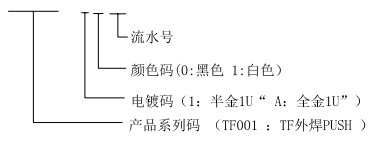
REV.	ZONE	LTR	DESCRIPTION	DATE	REVISER	APPD.
1.0						



RECOMMENDED P.C.B HOLE LAYOUT
COMPONENT SIDE VIEW(TOLERANCE:±0.05)

NOTES:

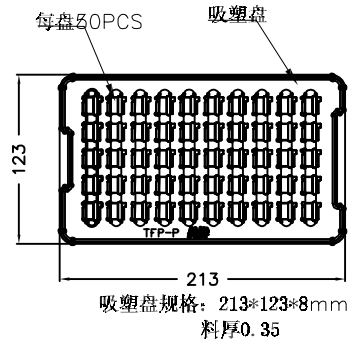
- MATERIAL:
HOUSING: HIGH TEMPERATURE THERMOPLASTIC
UL94V_0,COLOR:BLACK.
CONTACT: COPPER ALLOYS.
COVER: COPPER ALLOYS OR STEEL.
- PLATING:
UNDERPLATE: NICKEL.
CONTACT AREA: GOLD OVER NICKEL.
SOLDER AREA: TIN OVER NICKEL.
- MULTIMEDIA CARD COMPATIBLE
- PRODUCT NO. : TF001-1002



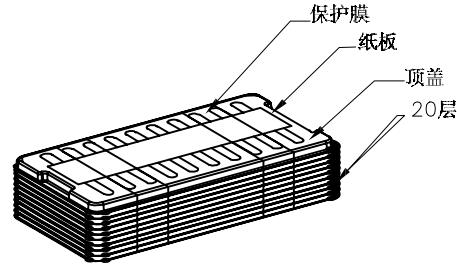
PIN NO.	NAME	YTYPE	DESCRIPTION
1	DAT2	I/O/PP	DATE LINE(BIT2)
2	CD/DAT3	I/O/PP	CARD DETECT DATE LIN(BIT3)
3	CMD	PP	COMMAND RESPONSE
4	VDD	S	SUPPLY VOLTAGE
5	CLX	I	CLOCK
6	VSS	S	SUPPLY VOLTAGE GROUND
7	DAT0	I/O/PP	DATE LINE(BIT0)
8	DAT1	I/O/PP	DATE LINE(DIT1)

MATERIAL:	TOLERANCE UNSPECIFIED: .000 ± 0.03 .00 ± 0.05 .0 ± 0.10 . ± 0.15 ANGLE ± 1°	SCALE: 1:1		UNIT: mm
		NAME: TF外焊 PUSH 有弹片		
FINISH:	DRAWN: Leo	DRAWING NO.:		
	DESIGNER: Leo	REV.: 1.0		
	CHECKED: Leo			
	APPROVED: Anda			

REV.	ZONE	LTR	DESCRIPTION	DATE	REVISER	APPD.
1.0						

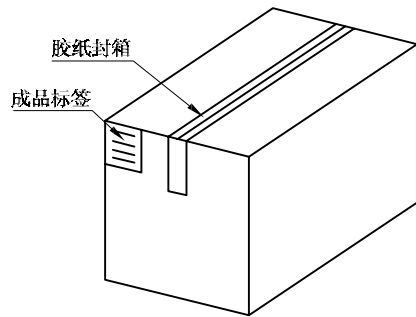


NO. 1



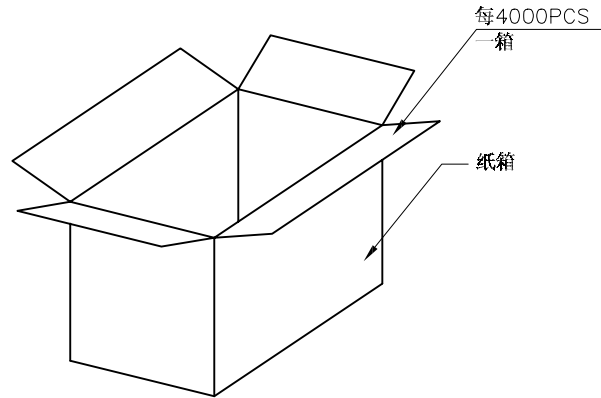
NO. 2

1. 材质要求:
- 1.1 纸箱的材质为B; 外形尺寸为26*22.5*19cm;
 - 1.2 PS盘的材质为PS, PS盘的外形尺寸213*123*8mm;
2. 包装要求:
- 2.1 每一盘装50PCS;
 - 2.2 每20盘累叠在一起, 共计1Kset, 上面需放一个空盘, 加一块纸板, 后用PE膜缠绕;
 - 2.3 把累叠好的PS盘放入纸箱中共计4Kset;
 - 2.4 把包装好的成品打包封箱, 并在纸箱外贴上标签;



纸箱规格: 26*22.5*19cm

NO. 4



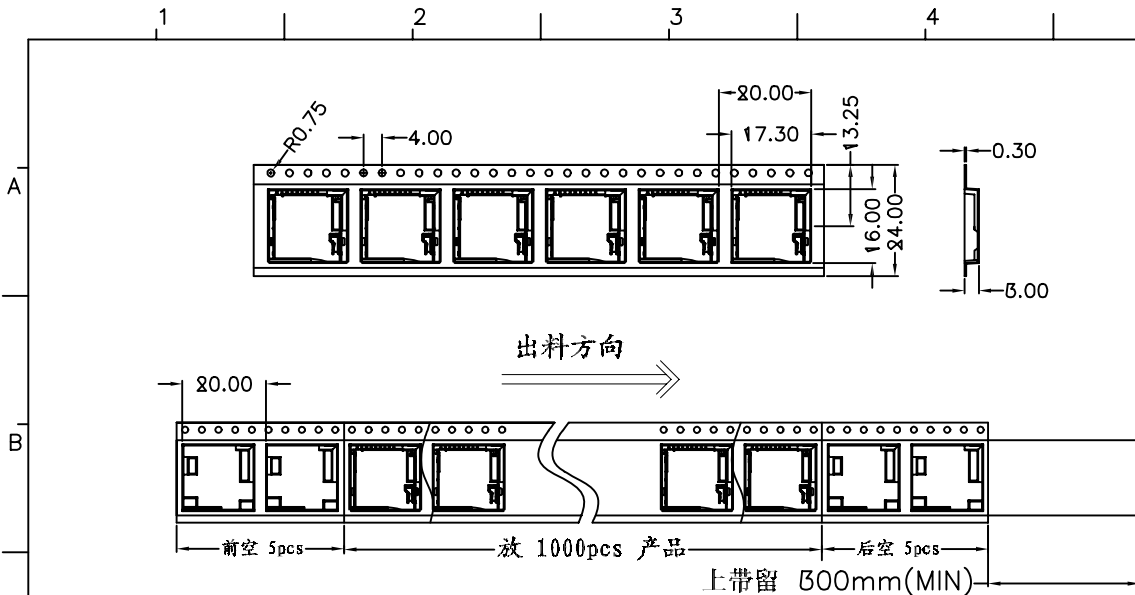
PRODUCT NO.: TF001-1001

流水号 (01: 盘装 02: 卷装)
颜色码 (0: 黑色 1: 白色)
电镀码 (1: 半金IU "A": 全金IU")
产品系列码 (TF001: TF外焊PUSH)

原旧料号: GSD-TF-9PWSX

MATERIAL:	TOLERANCE UNSPECIFIED: .0 0 0 ± 0.05 .0 0 ± 0.05 .0 ± 0.10 ± 0.15 ANGLE ± 1°	SCALE: 1:1		UNIT: mm
		NAME: TF外焊 PUSH		
FINISH:	DRAWN: Leo	DRAWING NO.: TF001-1001		REV.: 1.0
	DESIGNER: Leo			
	CHECKED: Leo			
	APPROVED: Anda			

REV.	ZONE	LTR	DESCRIPTION	DATE	REVISER	APPD.
1.0						

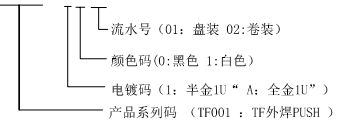


NO. 1

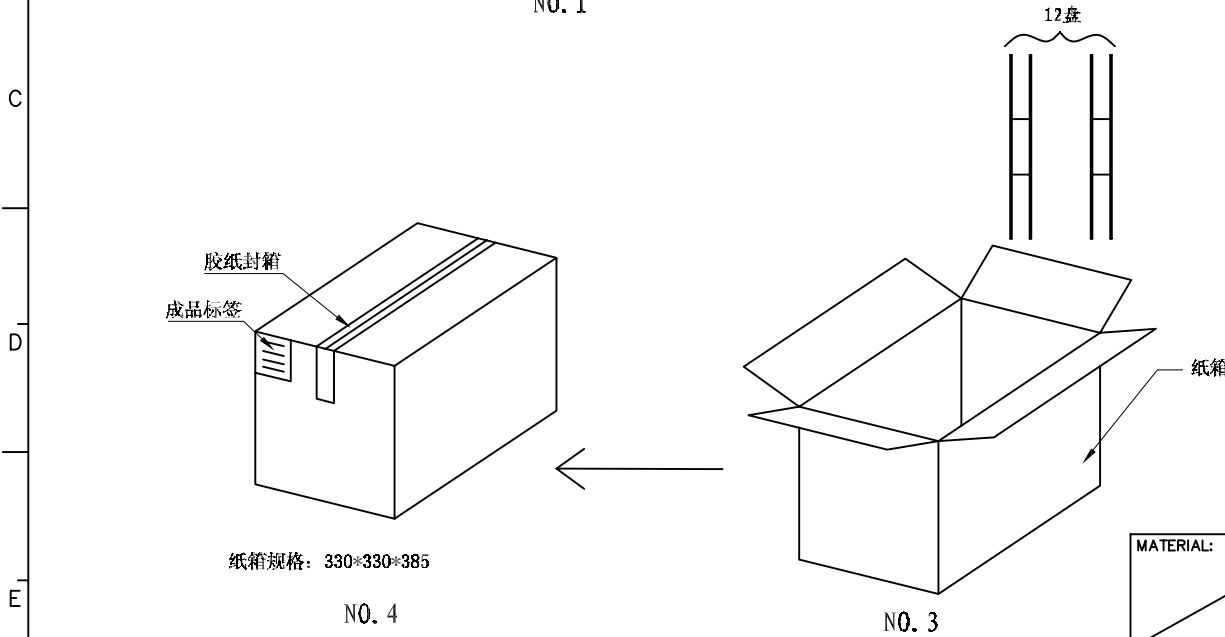
NO. 2

1. 材质要求:
- 1.1 纸箱的材质为B-B; 外形尺寸为33*33*38.5;
 - 1.2 卷盘的材质为PVC, 卷盘的外形尺寸为 $\phi 330 \times 30.4$;
 - 1.3 卷带的材质为PVC, 卷带的外形尺寸为20200*24.00*3.0mm;
2. 包装方式:
- 2.1 将卷带放入包装机后, 前空5PCS, 后放产品1000PCS, 再后空5PCS; 上带留300MM长度。
 - 2.2 将包装好的产品从包装机上取下并包装好;
 - 2.3 把照叠好的12盘叠放入纸箱中共计12Kset;
 - 2.4 把包装好的成品打包封箱, 并在纸箱外贴上标签

PRODUCT NO.: TF001-1001



原旧料号: GSD-TF-9PWSX



NO. 4

NO. 3

MATERIAL:	TOLERANCE UNSPECIFIED:		
	.0 0 0 ± 0.05 .0 0 ± 0.05 .0 ± 0.10 . ± 0.15 ANGLE ± 1°	SCALE:	UNIT:
FINISH:	DRAWN: Leo	NAME: TF外焊 PUSH	
	DESIGNER: Leo	SHEET: 1/1	
	CHECKED: Leo	DRAWING NO.: TF001-1002	
	APPROVED: Anda	REV.: 1.0	

Product specification

Prepared by: Je. Xia

Checked by: Ping. Gan

Approved by: Lion

Product Name	Part Number.	Rev.	Page No.
TF card push connector	GTF00X-X0-00X	C	2 / 11

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Product Name	Part Number.	Rev.	Page No.
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1. SCOPE

This product specification defines the product performance and the test methods to ascertain the performance of the **TF Memory card push connector**, which is designed and manufactured by ZUITA

2. REFERENCE DOCUMENTS

MIL-STD-1344A Test method for electrical connector **MIL-STD-202F** Test method for electrical components

EIA364 Test method for electrical components

JIS C 0051 Test method for electrical components

MIL-G-45204C Specification for gold plating

IEC-512-3 IEC standard for current carrying capacity tests

QQ-N-290A Specification for nickel plating

MIL-P-81728A Specification for tin/lead plating

MIL-T-10727B Specification for tin plating

UL498 UL standard for safety of attachment plug and receptacle

EN/ISO5961 Determination of total lead & cadmium content

EN1122 Determination of total lead & cadmium content

EN13346 Determination of heavy metals content

EPA3052 Determination of total lead & cadmium content

3. FEATURE & DIMENSIONS

3.1. PRODUCT DIMENSION

These connectors shall have the dimensions as shown in customer drawing.

3.2. PCB/PANEL LAYOUT

The recommended PCB layout is shown in customer drawing.

3.3. MATERIAL

The harmful material can follow the requirement of RoHS.

3.4. MECHANICAL & ELECTRICAL CHARACTERISTIC

The connector shall have the mechanical and electrical performance as described in table 1:

3.5. PACKAGING

Products shall be packaged according to requirements specified in purchase order for safe delivery. Products required tray or carrier tape should meet the proper specification per purchase order. Connector container and the packaging specification is shown in customer drawing.

3.6. MARKING

Manufacturer's name, industry recognized logo, or customer approved marks.

3.7. TRANSPORTATION

Any vehicle can be adopted for the transportation, but moisture-proof and no mechanical damage.

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3.8.STORAGE

Temperature: -25°C~+90°C, Relative humidity: ≤80%, Not to storage in corrosive environments A re-qualification test shall be conducted immediately while the storage duration exceed 6 months.

4. ENVIRONMENTAL

4.1. SOLDERABILITY

Connector's solderability can meet MIL-STD-202F standard. Finish shall be free of contaminants.

4.2. RESISTANCE TO SOLDER HEAT

4.2.1. Wave Soldering

Consists of three consecutive phases.

4.2.1.1. Preheat

Increase in temperature not to exceed 4°Cper second. Final preheat temperature will be within 125°Cof solder temperature..

4.2.1.2. Soldering

Device leads will be exposed to solder wave at 260°Cfor a maximum of 5 seconds.

4.2.1.3. Cool Down

Cool down in ambient air at approximately 20°Cto 25°C.

4.2.2. INFRARED REFLOW

Three cycles. Each cycle consisting of three consecutive phased.

4.2.2.1. Preheat

Increase in temperature not to exceed 4°C per second.

4.2.2.2. Soldering

Maximum allowable time above reflow temperature of 183 °C is 90 seconds. Maximum temperature in this interval is 260°C, not to exceed 10 seconds.

4.2.2.3. Cool Down

Cool down shall not exceed 6°C per second. **Note:** (注) Device temperature measurements are referenced from the top-center of the package outer surface.

4.3. CLEANING

Connectors resist to cleaning process. Aqueous Cleaning: Three cycles; each cycle consisting of a maximum of one minute exposure to 54°C to 66°C demineralized tap water at a maximum pressure of 30 psi; followed by air drying for 60°Cto 90 seconds at 93°C to 121°C.

5.Ratings

7.1. Current Rating : 0.5A

7.2. Voltage Rating : 5V

7.3 Voltage:200V AC/DC

7.4. Operating temperature : -20°C to 60°C

Humidity : 90% max. non condensing 。

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5. PERFORMANCE AND TEST DESCRIPTION

5.1. REQUIREMENT

Product is designed to meet electrical, mechanical, and environmental performance requirements specified in **Table I**.

5.2. TEST CONDITION

Unless otherwise specified, all tests shall be performed at ambient environmental conditions.

5.3. SAMPLE SELECTION

Test samples shall be selected at random from current production. No test samples shall be reused. Samples are pre-conditioned with 10cycles of durability. Each group shall be containing 5 test samples.

5.4. TEST SEQUENCE

Products qualification test sequence as shown in **Table II**.

6. QUALITY ASSURANCE PROVISIONS

ZUITA is responsible for the quality of the part as it is delivered to customer. Failing lots will be return or other supplier corrective action.

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TABLE I: PERFORMANCE REQUIREMENTS

Items	Requirements	Test Methods
1. Confirmation of Product	Product shall be conforming to the requirements of applicable product drawing.	Visually, dimensions and functionally inspected per applicable product drawing.
2. Contact resistance (Low Level)	initial 50 m Ω Max after 100 m Ω Max	Subject mated contacts assembled in housing to closed circuit of 100 mA max. at open circuit voltage of 20 mV max.
3. Insulation resistance	500 MΩ Min.	Measure by applying test potential between the adjacent contacts, and between the contacts and ground in the mated connector. MIL-STD-202, Method 302, Condition B (500 V DC \pm 10%).
4. Dielectric Strength	Connector must withstand test potential of 500 V AC for 1 minute. Current leakage must be 1.0 mA max..	Measure by applying test potential between the adjacent contacts, and between the contacts and ground in the mated connector. MIL-STD-202, Method 301.
5. Durability (Repeated Mating/Unmating)	Contact Resistance: 100 m Ω Max. And insertion/extraction force must meet the association specification. After testing.	Mate and the un-mate connector for 3000cycle.The insertion force under 1.2kg Max, and the extraction force meets 0.7kg Min, 1.2kg Max mate and unmated connectors for 300 cycles per hour.
6. Temperature rise	30 $^{\circ}$ C Max. 不高于30 $^{\circ}$ C	Carry rated current load.0.3A per contact.
7.Vibration Sinusoidal Low Frequency	No electrical discontinuity greater then 1 μ sec (s) shall occur. Contact resistance: 100 mΩ max.	Subject mated connector to 10-55-10 Hz traversed in 1 minute at 1.5 mm amplitude 2 hours each of 3 mutually perpendicular plane, 10 mA applied MIL-STD-202, Method 201.

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8. Shock	No electrical discontinuity greater than 1 μ sec. shall occur. No damage to product.	Applying an appropriate holder is allowed in vibration test and shock test. MIL-STD-202, Method 213,490m/s ² , 3 axes.
Items	Requirements	Test Methods
9. Thermal shock	No damage, Contact Resistance (Low Level) (Final) 100 mΩ max.	Temperature range from -55°C to +85°C .Start from -55°C. After 30 min. change to +85°C, change time is no more than 30 seconds. Total 5 cycles. MIL-STD-202, Method 107D,condition A.
10. Humidity	No damage, Contact Resistance (Low Level) (Final) 100 mΩ max. . Dielectric Strength should be OK, Insulation Resistance should be 100 M Ω min.	Temperature :40 \pm 2° C 96 hours. Relative humidity: 90-95%; Duration: 96 Hours. MIL-STD-202, Method 103,
11.Solderability	Appearance of the specimen shall be inspected after the test with the assistance of a magnifier capable of giving a magnification of 10 X for any damage such as pinholes, void or rough surface.	Soldering time: 3 to 5 Seconds Temperature: 260 \pm 5°C.
12.Resistance to soldering heat	No damage	Leave subject product in the 260 \pm 5°C chamber for 2 minutes.
13. Salt Spray	Contact Resistance (Low Level) (Final) 100 mΩ max.	5 \pm 1% salt concentration 12 \pm 4 hours 35 \pm 2°C MIL-STD-202, Method 101 Condition B.。
14.High temperature	Contact resistance: 100 mΩ max.	Subject product to 85 \pm 2°C for 96 hours continuously. MIL-STD-202, Method 108.

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TABLE II: PRODUCT QUALIFICATION TEST SEQUENCE

Test Description	Test Group					
	A	B	C	D	E	F
Appearance	1,6	1,3	1,5	1,6	1,5	1,3
Contact Resistance	2		2,4	2,5	2,4	
Insulation Resistance	3			3		
Dielectric Withstanding Voltage		2				
Durability			3			
Mating Force	4					
Un mating Force	5					
Humidity Resistance				4		
Salt Spray					3	
Solderability						2

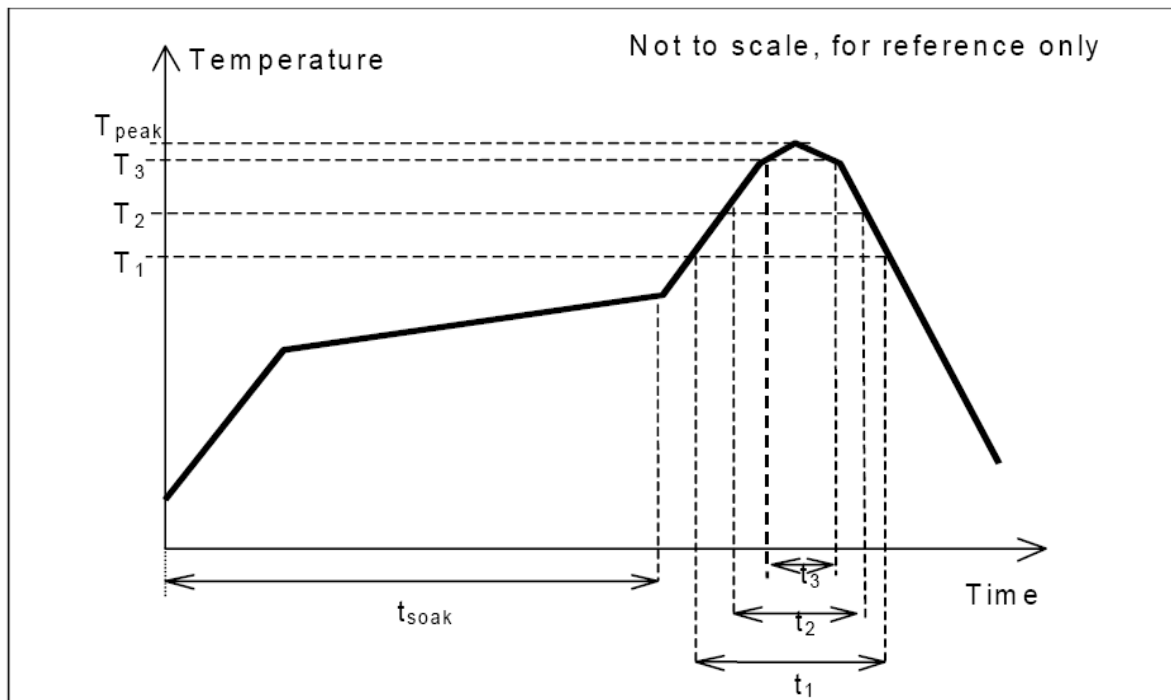
Product Name	Part Number.	Rev.	Page No.
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TABLE III:

REFLOW SOLDERING PROFILE

Pb-free reflow profile requirements:

Parameter	Reference	Specification
Average temperature gradient in preheating		2.5°C/s
Soak time	t _{soak}	2-3 minutes
Time above 217°C	t ₁	60 s
Time above 230°C	t ₂	50 s
Time above 245°C	t ₃	5 s
Peak temperature in reflow	T _{peak}	250°C (+/-5°C)
Temperature gradient in cooling		Max -5°C/s



This profile is the minimum requirement for evaluating soldering heat resistance of components. Heat transfer method used for reflow soldering is hot air convection. The actual air temperatures used to achieve the specified profile is higher and largely dependent on the reflow equipment.

Product Name	Part Number.	Rev.	Page No.
TF card push connector	GTF00X-X0-00X	C	11 / 11

Test Report

Product Name : TF Memony card connector

Product No. : ZTF00X-X0-00X

Sample Quantity : 30 PCS

Test Item : Reliability Test

Test Dept. : QA Dept.

Report No. : 201005 28001

Total Pages : 12 Pages

Date : 2015.03.25

Approved by		Checked by	/	Prepared by	
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Sample Model/Type : TF Memony card connector / 1130-11301-10A																				
Receiving Date : 2015.03.24																				
Test Time : 2015年03月25日8点15分-2015年04月28日18点30分																				
Test Requested Reliability Test																				
Test Method According to the Product Specification , Refer To MIL-STD-1344A/202F.																				
Lad Environmental : Temperature(温度) 20°C ± 10°C Humidity(湿度) 45% ± 5%RH																				
Results 1、Electrical Test <table border="0" style="width: 100%;"> <tr> <td style="width: 60%;">Contact Resistance</td> <td style="text-align: right;">PASS</td> </tr> <tr> <td>Dielectric Withstanding Voltage</td> <td style="text-align: right;">PASS</td> </tr> <tr> <td>Insulation Resistance</td> <td style="text-align: right;">PASS</td> </tr> </table> 2、Mechanical Test <table border="0" style="width: 100%;"> <tr> <td style="width: 60%;">Durability</td> <td style="text-align: right;">PASS</td> </tr> <tr> <td>Mating Force</td> <td style="text-align: right;">PASS</td> </tr> <tr> <td>Un mating Force</td> <td style="text-align: right;">PASS</td> </tr> <tr> <td>Contact Retention Force</td> <td style="text-align: right;">PASS</td> </tr> </table> 3、Environmental Test <table border="0" style="width: 100%;"> <tr> <td style="width: 60%;">Humidity Resistance</td> <td style="text-align: right;">PASS</td> </tr> <tr> <td>Salt Spray</td> <td style="text-align: right;">PASS</td> </tr> <tr> <td>Solderability</td> <td style="text-align: right;">PASS</td> </tr> </table>	Contact Resistance	PASS	Dielectric Withstanding Voltage	PASS	Insulation Resistance	PASS	Durability	PASS	Mating Force	PASS	Un mating Force	PASS	Contact Retention Force	PASS	Humidity Resistance	PASS	Salt Spray	PASS	Solderability	PASS
Contact Resistance	PASS																			
Dielectric Withstanding Voltage	PASS																			
Insulation Resistance	PASS																			
Durability	PASS																			
Mating Force	PASS																			
Un mating Force	PASS																			
Contact Retention Force	PASS																			
Humidity Resistance	PASS																			
Salt Spray	PASS																			
Solderability	PASS																			
Conclusion 结论: After finishing according to the product specification, the samples must compliant with the product specification.																				

1. Test Method & Criteria

The test sequence/group and result of TABLE I is based on the Product Specification of received samples and have been using is this test.。

TABLE I : Test Sequence/Group

Test Item	A	B	C	D	E	F
	sequence	sequence	sequence	sequence	sequence	sequence
Appearance	1,7	1,3	1,5	1,6	1,5	1,3
Contact Resistance	2		2,4	2,4	2,4	
Insulation Resistance	3			5		
Dielectric Withstanding Voltage		2				
Durability			3			
Mating Force	4					
Un mating Force	5					
Humidity Resistance				3		
Salt Spray					3	
Solderability						2
Sample Quantity	5	5	5	5	5	5
Sample No.	A1 ↓ A5	B1 ↓ B5	C1 ↓ C5	D1 ↓ D5	E1 ↓ E5	F1 ↓ F5

Table II: Performance Requirements		
Items	Test Methods	Requirements
1. Confirmation of Product	Product shall be conforming to the requirements of applicable product drawing.	Visually, dimensions and functionally inspected per applicable product drawing.
2. Contact Resistance	When measured at 20mV max open circuit at 100mA	30mΩ Max.
3. Insulation resistance	D.C100V is applied between adjacent contacts and insulation resistance is measured within one minute.	1000MΩ Min
4. Dielectric Withstanding Voltage	500V AC for 1 minute between adjacent contact and shell	No short circuiting and damage
5. Mating Force	Insertion is conducted between applicable connectors	1.4kg Max
6. unmating Force	Separation is conducted between applicable connectors	0.2kg Min
7. Datability	5000cycles of inserting and separating actions, action speed: under 600/hr	Contact Resistance: 100 mΩ Max. No crack or damage
8. Humidity resistance	Test temp: 40°C Test time: 96hr Test humidity: 90-95% Placing way: no conducted leave	Contact resistance: 100 mΩ Max. No Crack or expanding of part insulation tesistance: 10MΩmin
9. Salt Spray	Salt water density of 5%, 35° for 12 hours	There shall be no exposure of base metal of contact Contact resistance: 100 mΩ Max.
10. Solderability	The solder tails shall be dipped in a solder bath at 235±5°C for 3±0.5sec.	More than 95% of the dipped part shall be covered with solder

2. Test Equipment

Test Item	Equipment Name	Brand	Model	Equipment Photo
Contact Resistance	Milliohm Meter	常惠电子	TH2511	
Effective Date Correction: 2015.1.29 至 2016.1.28				
Dielectric Strength	AC/DC Withstanding Voltage Tester	友骏	19052	
Effective Date Correction: 2015.1.29 至 2016.1.28				
Insulation Resistance	Megohm Meter	友骏	19052	
Effective Date Correction: 2015.1.29 至 2016.1.28				
Durability	Durability Tester	OMOA 奥兰	OM-89800	
Effective Date Correction: 2015.1.29 至 2016.1.28				
Humidity	Temp & humidity Chamber	C.T.I 扬程仪器	QA-LP-40	
Effective Date Correction: 2015.2.26 至 2016.2.25				
Solderability	Solderability Tester	日本	SAT-5100	
Effective Date Correction: 2015.1.29 至 2016.1.28				
Salt Spray	Standard Salt Spray Tester	YO. JINN 友骏	SH-60	
Effective Date Correction: 2015.1.29 至 2016.1.28				

Test Item	Equipment Name	Brand	Model	Equipment Photo
Mating Force ; Un mating Force; Contact Retention Force; Durability;	电脑全自动插拔力机	友骏	1220S	
Effective Date Correction: 2015.1.29 至 2016.1.28				

3. Summary of Test Result

Table 1-1

Group A (Step1-Step7): Confirmation of Product

Sample No. Test Item	A1		A2		A3		A4		A5	
	Step1	Step7	Step1	Step7	Step1	Step7	Step1	Step7	Step1	Step7
Test Condition	Visually, dimensions and functionally inspected per applicable product drawing.									
Test Criteria	Product shall be conforming to the requirements of applicable product drawing.									
Result	Pass									

Table 1-2

Group A (Step2): Contact Resistance

Units: (m Ω)

Sample No. Pin No.	A1	A2	A3	A4	A5
	Step2	Step2	Step2	Step2	Step2
Pin 1	24.50	29.96	16.12	19.20	22.12
Pin 2	25.04	24.77	25.45	15.07	21.74
Pin 3	24.03	24.54	25.12	16.17	21.33
Pin 4	25.42	24.25	26.22	25.43	23.30
Test Condition	When measured at 20mV max open circuit at 100mA				
Test Criteria	50mΩ Max.				
Result	Pass				

Table 1-3

Group A (Step3): Insulation Resistance

Units: (m Ω)

Sample No. Pin No.	A1	A2	A3	A4	A5
	Step3	Step3	Step3	Step3	Step3
Pin 1~2	/	/	/	/	/
Pin 2~3	/	/	/	/	/
Pin 3~4	/	/	/	/	/
Test Condition	D.C100V is applied between adjacent contacts and insulation resistance is measured within one minute.				
Test Criteria	1000MΩ Min				
Result	Pass				

Table 1-4

Group A (Step4): Mating Force

Units (N f)

Sample No. Test Times	A1	A2	A3	A4	A5
	Step4	Step4	Step4	Step4	Step4
1 次	1. 25	1. 36	1. 15	1. 05	1. 11
2 次	1. 15	1. 26	1. 15	1. 35	1. 11
3 次	1. 25	1. 36	1. 15	1. 05	1. 11
4 次	1. 15	1. 26	1. 15	1. 35	1. 11
5 次	1. 25	1. 36	1. 15	1. 05	1. 11
6 次	1. 15	1. 26	1. 15	1. 35	1. 11
Test Condition	Insertion is conducted between applicable connectors				
Test Criteria	1.4kg Max				
Result	Pass				

Table 1-5

Group A (Step5): Un mating Force

Units (N f)

Sample No. Test Times	A1	A2	A3	A4	A5
	Step5	Step5	Step5	Step5	Step5
1 次	0. 23	0. 32	0. 23	0. 32	0. 23
2 次	0. 25	0. 33	0. 25	0. 33	0. 25
3 次	0. 20	0. 29	0. 20	0. 29	0. 20
4 次	0. 32	0. 28	0. 32	0. 28	0. 32
5 次	0. 40	0. 45	0. 40	0. 45	0. 40
6 次	0. 50	0. 36	0. 50	0. 36	0. 50
Test Condition	Separation is conducted between applicable connectors				
Test Criteria	0.2kg Min				
Result	Pass				

Table 2-1

Group B (Step1-Step3): Confirmation of Product

Sample No. Test Item	B1		B2		B3		B4		B5	
	Step1	Step3	Step1	Step3	Step1	Step3	Step1	Step3	Step1	Step3
Test Condition	Visually, dimensions and functionally inspected per applicable product drawing.									
Test Criteria	Product shall be conforming to the requirements of applicable product drawing.									

Result	Pass
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Table 2-2

Group B (Step2): Dielectric withstanding voltage

Sample No. Pin No.	B1		B2		B3		B4		B5	
	Step2	Step2	Step2	Step2	Step2	Step2	Step2	Step2	Step2	Step2
Pin 1~2	No short circuiting and damage(无短路现象)									
Pin 2~3										
Pin 3~4										
Test Condition	500V AC for 1 minute between adjacent contact and shell									
Test Criteria	No short circuiting and damage									
Result	Pass									

Table 3-1

Group C (Step1-Step6): Confirmation of Product

Sample No. Test Item	C1		C2		C3		C4		C5	
	Step1	Step6	Step1	Step6	Step1	Step6	Step1	Step6	Step1	Step6
Test Condition	Visually, dimensions and functionally inspected per applicable product drawing.									
Test Criteria	Product shall be conforming to the requirements of applicable product drawing.									
Result	Pass									

Table 3-2

Group C (Step2- Step4): Contact Resistance

Units(mΩ)

Sample No. Pin No.	C1		C2		C3		C4		C5	
	Step2	Step4	Step2	Step4	Step2	Step4	Step2	Step4	Step2	Step4
Pin 1	24.75	23.27	22.62	25.62	25.23	28.95	24.76	18.62	26.77	22.58
Pin 2	24.28	23.25	21.34	25.08	23.17	27.25	25.33	22.11	18.23	21.15
Pin 3	23.15	23.54	22.17	24.68	22.12	25.32	24.36	21.52	19.66	18.45
Pin 4	23.16	24.38	23.27	24.25	23.13	24.25	25.43	20.37	21.32	22.11
Test Condition	When measured at 20mV max open circuit at 100mA									
Test Criteria	30mΩ Max. Final:100 mΩ Max									
Result	Pass									

Table 3-3

Group C (Step3): Durability

Sample No.	C1	C2	C3	C4	C5
Pin No.	Step3	Step3	Step3	Step3	Step3
Durability					
Test Condition	5000cycles of inserting and separating actions, action speed:under600/hr				
Test Criteria	Contact Resistance:100 mΩ Max. No crack or damage				
Result	Pass				

Table 4-1

Group D (Step1- Step6): Confirmation of Product

Sample No.	D1		D2		D3		D4		D5	
Test Item	Step1	Step6	Step1	Step6	Step1	Step6	Step1	Step6	Step1	Step6
Test Condition	Visually, dimensions and functionally inspected per applicable product drawing.									
Test Criteria	Product shall be conforming to the requirements of applicable product drawing.									
Result	Pass									

Group D (Step5): Insulation Resistance

Units :(MΩ)

Sample No.	D1	D2	D3	D4	D5
Pin No.	Step5	Step5	Step5	Step5	Step5
Pin 1~2	/	/	/	/	/
Pin 2~3	/	/	/	/	/
Pin 3~4	/	/	/	/	/
Test Condition	D.C100V is applied between adjacent contacts and insulation resistance is measured within one minute.				
Test Criteria	1000MΩ Min, Final: 10MΩmin				
Result	Pass				

Table 4-4

Group D (Step3): Humidity Resistance

Sample No.	D1	D2	D3	D4	D5
Pin No.	Step3	Step3	Step3	Step3	Step3
Test Condition	Test temp:40℃ Test time:96hr Test humidity:90-95% Placing way: no conducted leave				
Test Criteria	Contact resistance:100 mΩ Max. No Crack or expanding of part insulation tesistance:10MΩmin				

Result	Pass
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Table 5-1

Group E (Step1- Step5): Confirmation of Product

Sample No.	E1		E2		E3		E4		E5	
	Step1	Step5	Step1	Step5	Step1	Step5	Step1	Step5	Step1	Step5
Test Item										
Test Condition	Visually, dimensions and functionally inspected per applicable product drawing.									
Test Criteria	Product shall be conforming to the requirements of applicable product drawing.									
Result	Pass									

Table 5-2

Group E (Step2- Step4): Contact Resistance

Units(mΩ)

Sample No.	E1		E2		E3		E4		E5	
	Step2	Step4	Step2	Step4	Step2	Step4	Step2	Step4	Step2	Step4
Pin 1	22.33	21.35	25.52	24.55	22.38	22.58	28.51	24.94	23.31	26.64
Pin 2	24.52	27.66	25.32	27.52	25.45	21.15	24.24	19.23	20.32	18.56
Pin 3	26.33	27.33	24.19	24.17	23.45	18.45	20.13	22.33	24.92	23.54
Pin 4	27.85	25.35	28.65	25.63	25.52	22.11	17.95	19.65	21.36	25.08
Test Condition	When measured at 20mV max open circuit at 100mA									
Test Criteria	30mΩ Max. Final:100 mΩ Max.									
Result	Pass									

Table 5-3

Group E (Step3): Salt Spray

Sample No.	E1	E2	E3	E4	E5
	Step3	Step3	Step3	Step3	Step3
Pin No.					
Test Condition	Salt water density of5%, 35°for 12hours				
Test Criteria	There shall be no exposure of base metal of contact Contact resistance:100 mΩ Max.				
Result	Pass				

Table 6-1

Group F (Step1- Step3): Confirmation of Product

Sample No.	F1		F2		F3		F4		F5	
	Step1	Step3	Step1	Step3	Step1	Step3	Step1	Step3	Step1	Step3
Test Item										
Test Condition	Visually, dimensions and functionally inspected per applicable product drawing.									
Test Criteria	Product shall be conforming to the requirements of applicable product drawing.									
Result	Pass									

Table 6-2

Group F (Step2): Solderability

Sample No.	F1	F2	F3	F4	F5
	Step2	Step2	Step2	Step2	Step2
Test Item					
Test Condition	The solder tails shall be dipped in a solder bath at $235\pm 5^{\circ}\text{C}$ for $3\pm 0.5\text{sec}$.				
Test Criteria	More than 95% of the dipped part shall be covered with solder				
Result	Pass				